

## Product Specification

|              |                         |
|--------------|-------------------------|
| Product:     | Conductive Silver Paste |
| Part Number: | 01M-3505                |

### Application Scope :

This product is suitable for zinc oxide pressure sensitive ceramic electrode.

### Usage Conditions :

|                  |  |
|------------------|--|
| Substrate        | Zinc oxide ceramic   |
| Printing         | 200-300 mesh screen printing   |
| Leveling         | Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).   |
| Drying           | Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted according to actual conditions).  |
| Firing Condition | The sintering temperature is 600°C (recommended value) and the sintering time is 10 minutes.<br>The slurry has a broad sintering temperature range, adjustable between 480-750°C as needed, with the peak temperature maintained for 10 minutes. |
| Thinner          | ST-1000  |

### Characteristics :

#### 1. Paste Characteristics :

| Characteristic | Standard    | Test Method And Conditions  |
|----------------|-------------|---|
| 1 Fineness     | ≤5μm        | FOG test  |
| 2 Viscosity    | 160-280Pa.s | Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10 rpm, with viscosity adjustable to 25±1°C according to user requirements. |

#### 2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12μm.)

| Characteristics |                   | Standard                       | Test Method And Conditions  |
|-----------------|-------------------|--------------------------------|---|
| 3               | Resistivity       | $\leq 7\text{m}\Omega/\square$ | Test pattern 0.6mm×60mm   |
| 4               | Adhesion Strength |                                | Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad.<br>Solder: 96.5Sn/0.5Cu Mildly activated flux used. |
|                 | Initial Adhesion  | $\geq 50\text{N}$              |   |

**Save Conditions And Validity Period :**

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

**Packaging Method :**

Standard packaging, 1000g/can; samples are available in 200g small can packaging.